

For immediate release

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### **NEXX Systems Announces Sale of Nimbus XP and Stratus 200 to Unisem (M) Berhad of Malaysia**

**Billerica, MA – October 4, 2005** – NEXX Systems, a leading provider of processing equipment for advanced wafer level packaging applications, today announced the sale of a Nimbus XP sputtering deposition system and a Stratus 200 electrodeposition system to Unisem (M) Berhad. The two systems will be installed at Unisem's Ipoh facility in Malaysia and are expected to be in full production early in the first quarter of 2006.

Kevin Crofton, senior vice president of NEXX Systems noted, "The top management at Unisem selected NEXX Systems to provide the PVD and plating process equipment, due to superior process performance embedded in low cost of ownership platforms."

He added, "We are delighted to partner with Unisem in providing process solutions for their wafer bumping line. We believe the combination of the Nimbus XP for under bump metallization and the Stratus 200 for electrodeposition in Unisem's fab line will yield both superior product as well as significant economies, providing a winning solution for Unisem and their customers."

There are over 30 Nimbus systems in production worldwide, providing under bump metallization for advanced wafer-level packaging. The newly-introduced Stratus 200 is a revolutionary automated electrodeposition tool, incorporating ShearPlate™ technology that creates fluid agitation <2 mm from the wafer surface and achieving the fastest deposition of the most uniform metal films in the market today.

Unisem (M) Berhad is a leading semiconductor packaging and test services provider in Malaysia. Unisem and its wholly-owned subsidiary Unisem (Europe) Limited provide full turnkey solutions to its customers in wafer grinding, packaging and testing of ICs, tape and reel, and dropship services. Together with Unisem (Europe), Unisem has the capability of packaging and testing a wide range of leadframe and substrates packages. Unisem continues to work closely with its customers to develop the next generation of packages focusing its efforts on packages that meet customers' immediate demand.

NEXX Systems brings exceptional technical expertise to flip chip and advanced packaging. Our product lines provide the most efficient, yet affordable, systems of their kind: Nimbus for multi-layer sputter deposition of metals, and Stratus for high throughput electro-deposition of metals. Additional information can be found at: [www.nexxsystems.com](http://www.nexxsystems.com).

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